Equipment Information Sheet

Heidelberg MLA 150 Maskless Aligner

Manager: Giovanni Sartorello 607-254-4853 Calls to staff phones will be automatically forwarded to Backup: Garry Bordonaro 607-254-4936 Backup: Roberto Panepucci 607-254-4855 Backup: John Treichler 607-254-4949

their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY **USAGE RESTRICTIONS**

• Pieces only with automatic alignment substrate template

SCHEDULING/SIGN-UP RESTRICTIONS MATERIALS COMPATIBILITY CATEGORY

Minimum Tool Time: 30 minutes

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared- w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- No substrates smaller than 5 mm x 5 mm
- No Class 2 materials (SU-8, LOR, PGMI, Omnicoat) until a dedicated stage insert is available.

Last Updated: 03/20/2025